

STS4622-VB Datasheet

Dual N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)			
40	0.058 at V _{GS} = 10 V	3.6	4.0			
40	0.072 at V _{GS} = 4.5 V	3.0	4.0			

FEATURES

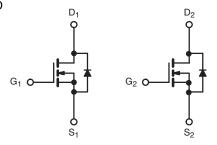
 Halogen-free According to IEC 61249-2-21 Definition



- Trench Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- CCFL Inverter
- DC/DC Converter
- HDD



N-Channel MOSFET

N-Channel MOSFET

		TSOP- Top Vie		
T	G1	1	6	D1
3 mm	S2 🔲	2	5	S1
<u> </u>	G2	3	4	D2
<u> </u>	- -	_ 2.85 mi	n _	

ABSOLUTE MAXIMUM RATINGS (TA	= 25 °C, unless other	rwise noted)			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V_{DS}	40	V		
Gate-Source Voltage		V_{GS}	± 20	, v	
	T _C = 25 °C		3.6		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	I _D	2.5		
Continuous Brain Current (1) = 130 °C)	T _A = 25 °C	'D	3.0 ^{b, c}		
	T _A = 70 °C		2.0 ^{b, c}		
Pulsed Drain Current (10 µs Pulse Width)		I _{DM}	20	Α	
Source-Drain Current Diode Current	$T_C = 25 ^{\circ}C$	Is	2.0	^	
Source-Drain Guitent Diode Guitent	T _A = 25 °C		1.4 ^{b, c}		
Pulsed Source-Drain Current	I _{SM}	20			
Single Pulse Avalanche Current L = 0.1 mH		I _{AS}	10		
Single Pulse Avalanche Energy		E _{AS}	5		
	$T_C = 25 ^{\circ}C$		1.3		
Maximum Power Dissipation	T _C = 70 °C	P_D	0.9	W	
Maximum Tower Dissipation	T _A = 25 °C	. р	1.0 ^{b, c}	**	
	T _A = 70 °C		0.75 ^{b, c}		
Operating Junction and Storage Temperature Range	T_J,T_stg	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Тур.	Max.	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	49	62.5	°C/W		
Maximum Junction-to-Foot (Drain)	Steady-State	R_{thJF}	30	40	0/11		

Notes:

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under steady state conditions is 120 $^{\circ}\text{C/W}.$



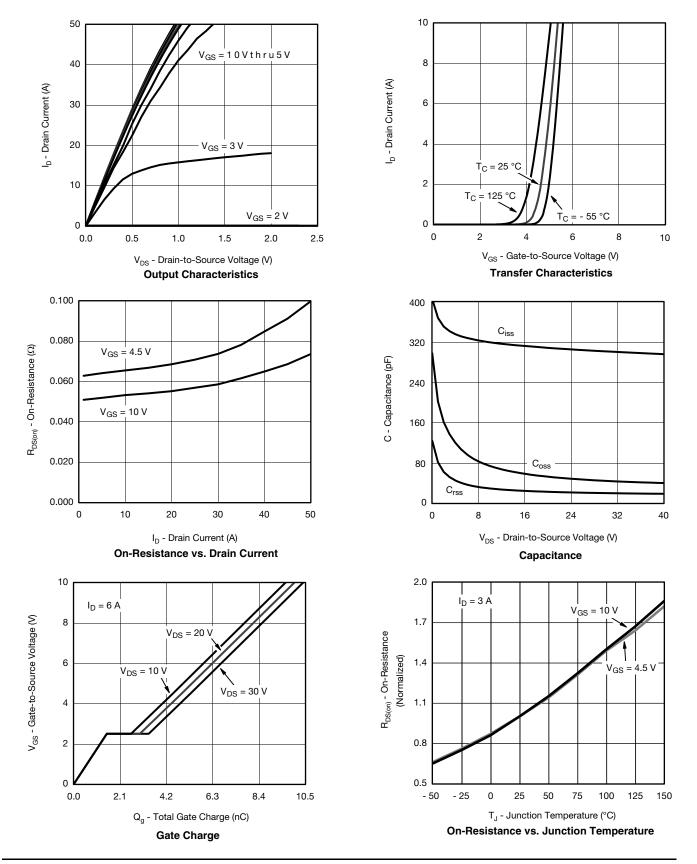
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit
Static						
Drain-Source Breakdown Voltage	age V_{DS} $V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$		40			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	V _{DS} /T _J		49		\//0C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- I _D = 250 μA		- 5.2		mV/°C
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0		2.0	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			100	nA
Zoro Cata Valtago Drain Current	1	V _{DS} = 40 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 55 °C			10	μΑ
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	20			Α
D : 0	D	V _{GS} = 10 V, I _D = 7.0A		0.058		0
Drain-Source On-State Resistance ^D	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 6.0 \text{A}$		0.072		Ω
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 7.0A		35		S
Dynamic ^a						
Input Capacitance	C _{iss}			280		
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, I_{D} = 1 \text{ MHz}$		50		pF
Reverse Transfer Capacitance	C _{rss}]		22		
Total Cata Chausa	0	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7.0 \text{ A}$		9.0		nC
Total Gate Charge	Q _g			4.5		
Gate-Source Charge	Q_{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 7.0 \text{ A}$		1.5		
Gate-Drain Charge	Q _{gd}			1.5		
Gate Resistance	R_g	f = 1 MHz	0.6	2.7	5.4	Ω
Turn-On Delay Time	t _{d(on)}			7	14	
Rise Time	t _r	$V_{DD} = 20 \text{ V}, R_L = 2 \Omega$		9	18	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 7.0 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		16	32	
Fall Time	t _f]		8	16	
Turn-On Delay Time	t _{d(on)}			12	24	ns
Rise Time	t _r	V_{DD} = 20 V, R_L = 2 Ω		10	20	7
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 7.0 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		13	26	
Fall Time	t _f	 		8	16	1
Drain-Source Body Diode Characteristi	cs					
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C		2.6		۸
Pulse Diode Forward Current ^a	I _{SM}			20		A
Body Diode Voltage	V_{SD}	I _S = 3 A		0.77	1.2	٧
Body Diode Reverse Recovery Time	t _{rr}			15	30	ns
Body Diode Reverse Recovery Charge Q _{rr}		I _F = 5 A, dl/dt = 100 A/μs, T _J = 25 °C		7.5	15	nC
Reverse Recovery Fall Time	t _a	$\frac{1}{1} = 3 \text{ A}, \text{ u/ut} = 100 \text{ A/}\mu\text{s}, \text{ I}_{\text{J}} = 25 \text{ C}$		9		
Reverse Recovery Rise Time	t _b	j		6		ns

Notes:

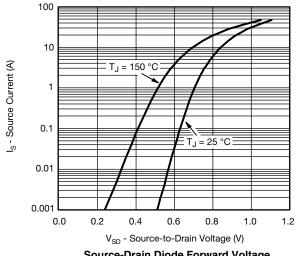
- a. Guaranteed by design, not subject to production testing. b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

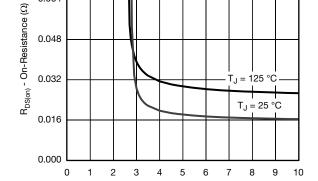
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.











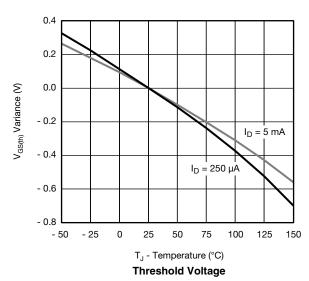
0.080

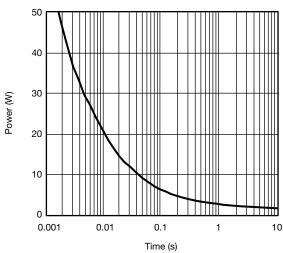
0.064

 $I_D = 3.0 A$

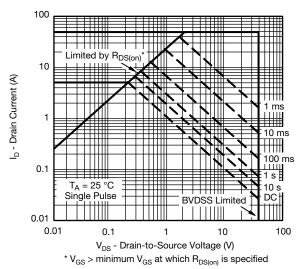
Source-Drain Diode Forward Voltage





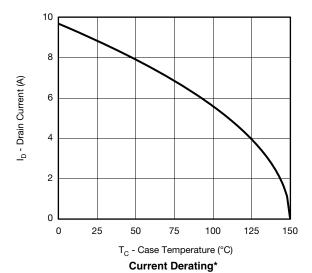


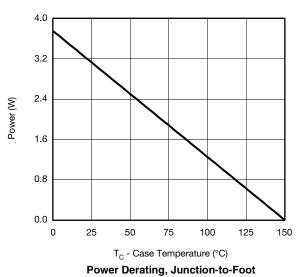
Single Pulse Power, Junction-to-Ambient

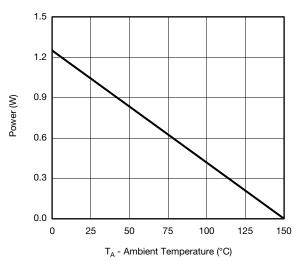


Safe Operating Area







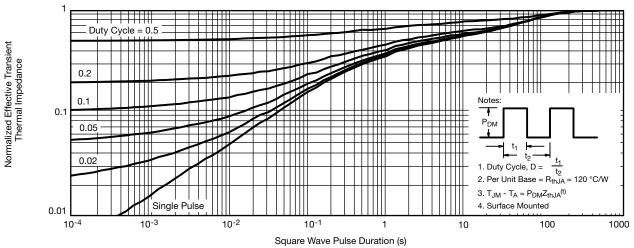


Power Derating, Junction-to-Ambient

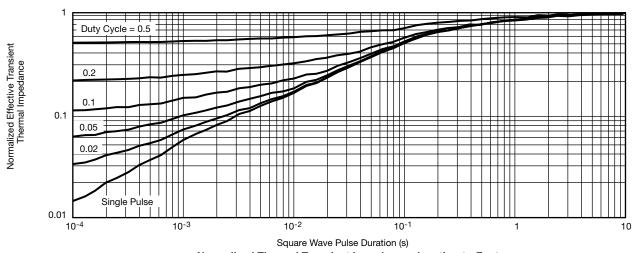
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^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

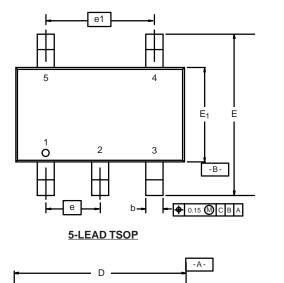


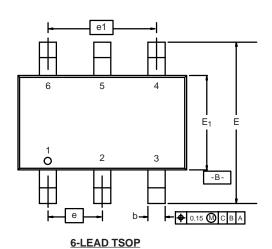
Normalized Thermal Transient Impedance, Junction-to-Foot

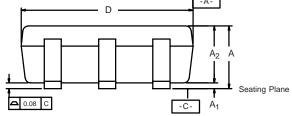


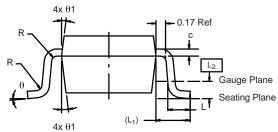
TSOP: 5/6-LEAD

JEDEC Part Number: MO-193C









	MILLIMETERS			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A ₁	0.01	-	0.10	0.0004	-	0.004	
A ₂	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.006	0.008	
D	2.95	3.05	3.10	0.116	0.120	0.122	
Е	2.70	2.85	2.98	0.106	0.112	0.117	
E ₁	1.55	1.65	1.70	0.061	0.065	0.067	
е	0.95 BSC			0.0374 BSC			
e ₁	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L ₁	0.60 Ref			0.024 Ref			
L ₂	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
θ_1		7° Nom		7° Nom			
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							

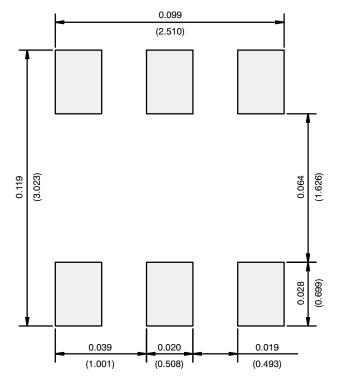
服务热线:400-655-8788

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RECOMMENDED MINIMUM PADS FOR TSOP-6



Recommended Minimum Pads Dimensions in Inches/(mm)



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